

30V N-Channel Enhancement-Mode MOSFET 30V N 沟道增强型 MOS 管

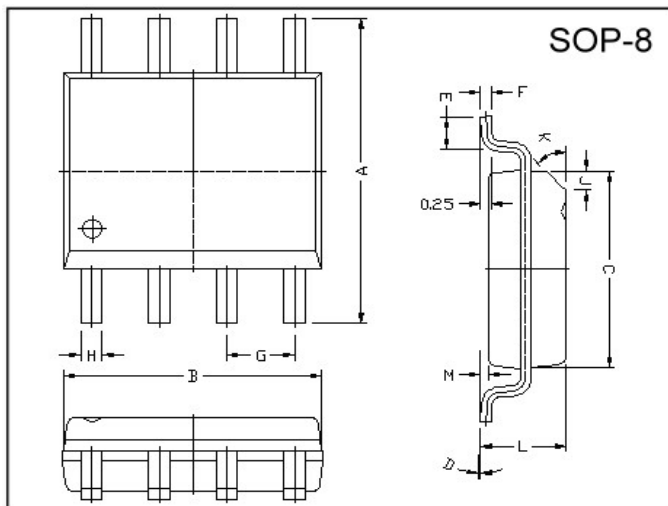
 $V_{DS} = 30V$ $R_{DS(ON)}, V_{GS}@10V, I_{DS}@12A = 10.5m\Omega$ $R_{DS(ON)}, V_{GS}@4.5V, I_{DS}@12A = 15m\Omega$ **Features 特性**

Advanced trench process technology 高级的加工技术

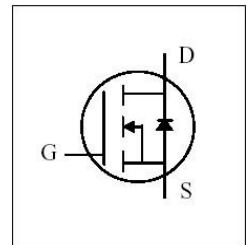
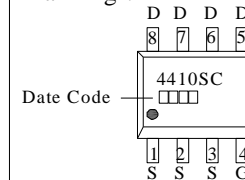
High Density Cell Design For Ultra Low On-Resistance 极低的导通电阻高密度的单元设计

Fully Characterized Avalanche Voltage and Current 完好的雪崩性能

Improved Shoot-Through FOM 改进的成型工艺

Package Dimensions 封装尺寸及外形图

Marking :



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.80	6.20	M	0.10	0.25
B	4.80	5.00	H	0.35	0.49
C	3.80	4.00	L	1.35	1.75
D	0°	8°	J	0.375 REF.	
E	0.40	0.90	K	45°	
F	0.19	0.25	G	1.27 TYP.	

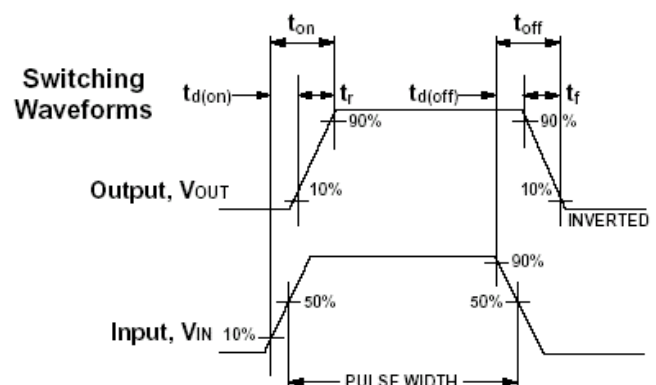
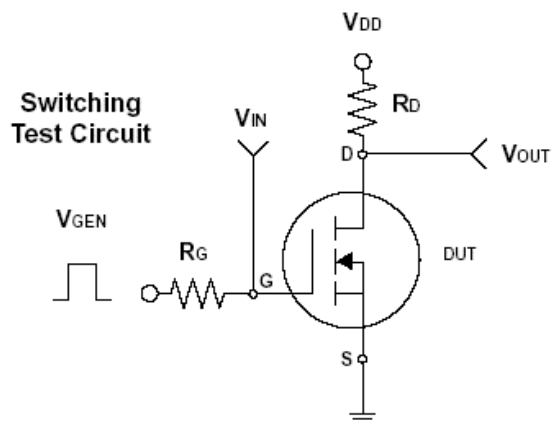
Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted) 25°C 极限参数和热特性

Parameter 极限参数	Symbol 符号	Limit 范围	Unit 单位
Drain-Source Voltage 漏源电压	V_{DS}	30	V
Gate-Source Voltage 栅源电压	V_{GS}	± 20	
Continuous Drain Current 连续漏极电流	I_D	12	A
Pulsed Drain Current ¹⁾ 脉冲漏极电流	I_{DM}	48	
Maximum Power Dissipation 最大耗散功率	P_D	2.5	W
		1.2	
Operating Junction and Storage Temperature Range 使用及储存温度	T_J, T_{stg}	-55 to 150	°C
Avalanche Energy with Single Pulse 雪崩能量	EAS	150	mJ
Junction-to-Case Thermal Resistance 结壳热阻	$R_{\theta JC}$	25	°C/W
Junction-to-Ambient Thermal Resistance (PCB mounted) ²⁾ 结环热阻	$R_{\theta JA}$	50	

ELECTRICAL CHARACTERISTICS 一般电气特性

Parameter 参数	符号	Test Condition 测试条件	最小值	典型值	最大值	单位
Static 静态参数						
Drain-Source Breakdown Voltage 漏源击穿电压	BV _{DSS}	V _{GS} = 0V, I _D = 250uA	30			V
Drain-Source On-State Resistance 漏源导通电阻	R _{DS(on)}	V _{GS} = 4.5V, I _D = 12A		11.0	15.0	mΩ
Drain-Source On-State Resistance 漏源导通电阻	R _{DS(on)}	V _{GS} = 10V, I _D = 12A		8.5	10.5	
Gate Threshold Voltage 开启电压	V _{GS(th)}	V _{DS} =V _{GS} , I _D = 250uA	1	1.8	3	V
Zero Gate Voltage Drain Current 0 栅压漏极电流	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	uA
Gate Body Leakage 漏极短路时截止栅电流	I _{GSS}	V _{GS} = ± 20V, V _{DS} = 0V			±100	nA
Forward Transconductance 正向跨导	g _{fs}	V _{DS} = 15V, I _D = 12A		64	—	S
Dynamic ³⁾ 动态参数						
Total Gate Charge 栅极总电荷	Q _g	V _{DS} = 15V, I _D = 12A V _{GS} = 5V		12	45	nC
Gate-Source Charge 栅-源极电荷	Q _{gs}			4.5		
Gate-Drain Charge 栅-漏极电荷	Q _{gd}			3.6		
Turn-On Delay Time 导通延迟时间	t _{d(on)}	V _{DD} = 15V, R _G = 6Ω I _D = 1A, V _{GS} = 10V		22	35	ns
Turn-On Rise Time 导通上升时间	t _r			13	20	
Turn-Off Delay Time 关断延迟时间	t _{d(off)}			82	125	
Turn-Off Fall Time 关断下降时间	t _f			30	45	
Input Capacitance 输入电容	C _{iss}	V _{DS} = 15V, V _{GS} = 0V f = 1.0 MHz		1180		pF
Output Capacitance 输出电容	C _{oss}			270		
Reverse Transfer Capacitance 反向传输电容	C _{rss}			145		
Source-Drain Diode 源漏二极管参数						
Max. Diode Forward Current 最大正向电流	I _S				2.0	A
Diode Forward Voltage 正向电压	V _{SD}	I _S = 2A, V _{GS} = 0V			1.5	V

Note: Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$ 注意：脉冲测试：脉冲宽度 $\leq 300\mu s$ 死区 $\leq 2\%$



N-Channel 30-V (D-S) MOSFET

Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)

